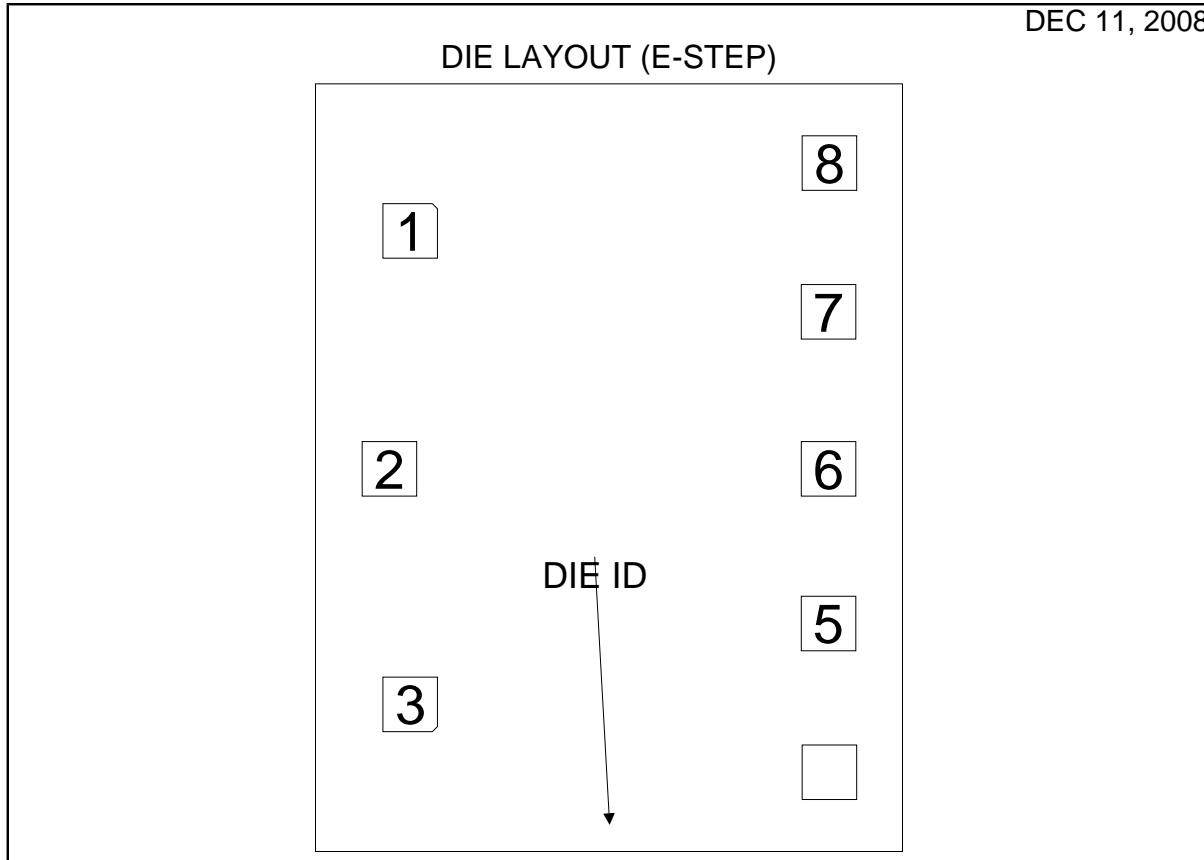


LM158A MDE MCD2860A
SMD#5962R8771003V9A
LOW POWER DUAL OPERATIONAL AMPLIFIER

DEC 11, 2008



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM158E	Bond Pad Opening Size (min)	92.00µm x 92.00µm
Die Step	E	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	VOM ONLY
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	990.60µm x 1295.40µm 39.0mils x 51.0mils	Back Side Connection	Floating
Thickness	304.8µm Nominal		
Min Pitch	261µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(E-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
Output B	1	-336	400	92	x	92
V +	2	-371	-2	92	x	92
Output A	3	-336	-400	92	x	92
Input A -	4	372	-514	92	x	92
Input A +	5	371	-263	92	x	92
Gnd	6	371	-2	92	x	92
Input B +	7	371	263	92	x	92
Input B -	8	372	514	92	x	92

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